

Description

The Si2302CDS-T1-E3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 20V I_D = 2.3 A$ $R_{DS(ON)} < 60m\Omega@ V_{GS} = 4.5V$

Application

Battery protection Load switch Uninterruptible power supply

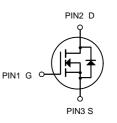
Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|-----------------|--------|------------|----------|
| Si2302CDS-T1-E3 | SOT-23 | HXY MOSFET | 3000 |

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

| Symbol | Parameter | Limit | Unit V | |
|------------------|--|------------|--------------|--|
| VDS | Drain-Source Voltage | 20 | | |
| V _G s | Gate-Source Voltage | ±12 | V | |
| ID | Drain Current-Continuous | 2.3 | A | |
| Ідм | Drain Current-Pulsed (Note 1) | 16 | A | |
| PD | Maximum Power Dissipation | 0.9 | W | |
| Tj,Tstg | Operating Junction and Storage Temperature Range | -55 To 150 | °C | |
| Reja | Thermal Resistance, Junction-to-Ambient (Note 2) | 139 | °C /W | |





N-Channel MOSFET



N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_A=25[°]C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Мах | Unit |
|----------------------------------|-------------------|---|-----|------|------|------|
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250µA 20 | | 22 | - | V |
| Zero Gate Voltage Drain Current | IDSS | V _{DS} =20V,V _{GS} =0V | | - | 1 | μA |
| Gate-Body Leakage Current | lgss | V _{GS} =±12V,V _{DS} =0V | - | - | ±100 | nA |
| Gate Threshold Voltage | VGS(th) | V _{DS} =V _{GS} ,I _D =250µA | 0.5 | 0.75 | 1.2 | V |
| | | V_{GS} =2.5V, I _D =2.0A | - | 54 | 72 | mΩ |
| Drain-Source On-State Resistance | Rds(on) | V _{GS} =4.5V, I _D =2.3A | - | 48 | 60 | mΩ |
| Forward Transconductance | gfs | V _{DS} =5V,I _D =2.3A | - | 8 | _ | S |
| Input Capacitance | C _{lss} | | - | 260 | - | PF |
| Output Capacitance | Coss | V _{DS} =10V,V _{GS} =0V, | - | 48 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | F=1.0MHz | - | 27 | - | PF |
| Turn-on Delay Time | td(on) | | - | 2.5 | - | nS |
| Turn-on Rise Time | tr | V _{DD} =10V, R∟=3.3Ω | - | 3.2 | - | nS |
| Turn-Off Delay Time | td(off) | V_{GS} =4.5V, R_{GEN} =6 Ω | - | 21 | - | nS |
| Turn-Off Fall Time | t _f | | - | 3 | - | nS |
| Total Gate Charge | Qg | | - | 2.9 | 5 | nC |
| Gate-Source Charge | Q _{gs} | V _{DS} =10V,I _D =2.3A, | - | 0.4 | - | nC |
| Gate-Drain Charge | Q _{gd} | V _{GS} =4.5V | - | 0.6 | - | nC |
| Diode Forward Voltage (Note 3) | Vsd | V _{GS} =0V,I _S =2.3A | - | 0.75 | 1.2 | V |
| Diode Forward Current (Note 2) | ls | | - | - | 3.3 | Α |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production



Si2302CDS-T1-E3 N-Channel Enhancement Mode MOSFET

Typical Electrical and Thermal Characteristics

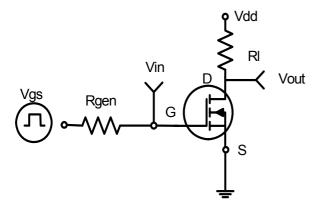


Figure 1:Switching Test Circuit

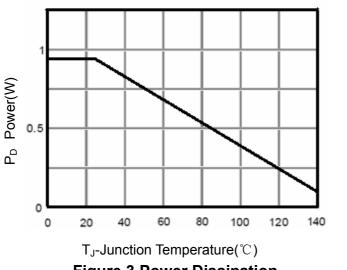
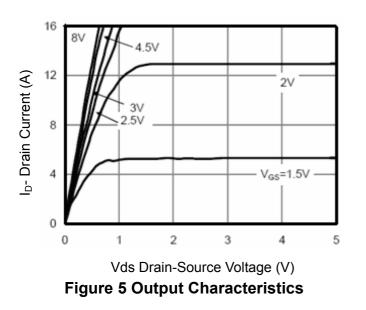
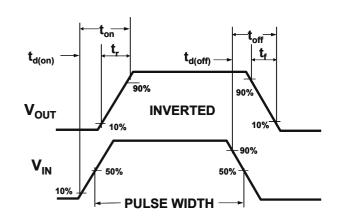


Figure 3 Power Dissipation







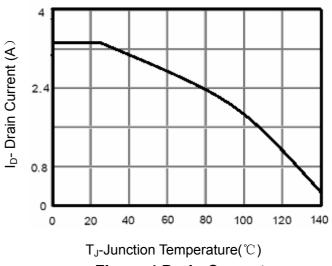


Figure 4 Drain Current

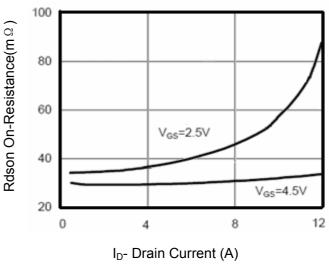
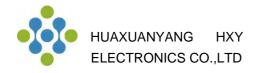
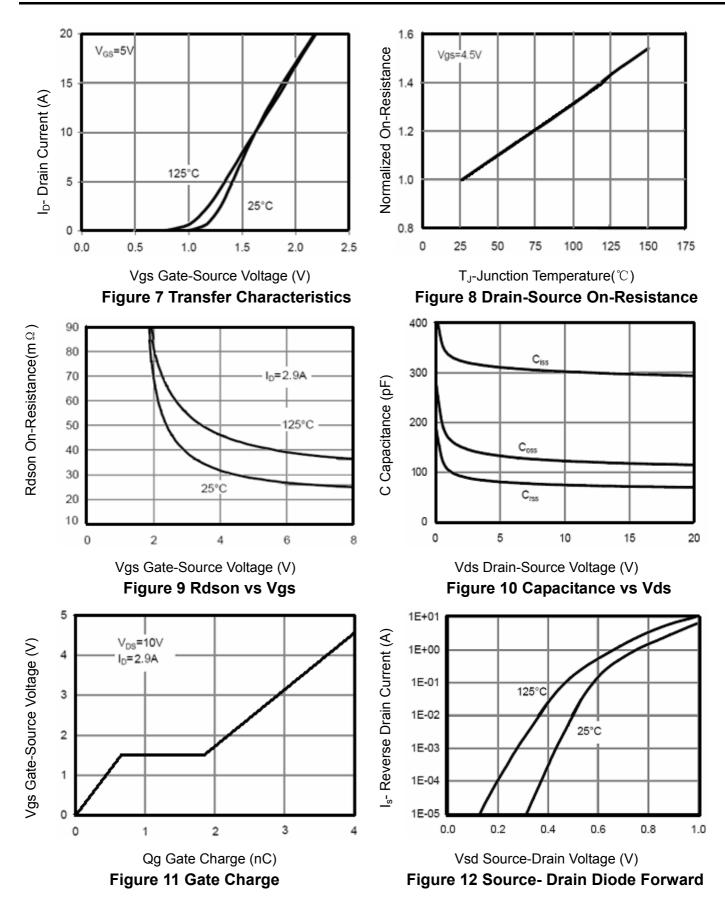


Figure 6 Drain-Source On-Resistance



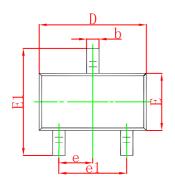
Si2302CDS-T1-E3

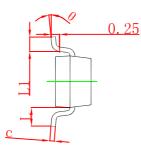
N-Channel Enhancement Mode MOSFET

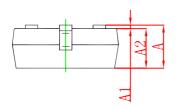




SOT-23 Package Outline Dimensions

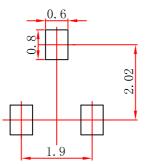






| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|-------|----------------------|-------|--|
| | Min | Max | Min | Max | |
| А | 0.900 | 1.150 | 0.035 | 0.045 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 | |
| b | 0.300 | 0.500 | 0.012 | 0.020 | |
| С | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 2.800 | 3.000 | 0.110 | 0.118 | |
| Е | 1.200 | 1.400 | 0.047 | 0.055 | |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 | |
| e | 0.950 TYP | | 0.037 TYP | | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 | |
| L | 0.550 REF | | 0.022 REF | | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 | |
| θ | 0° | 8° | 0° | 8° | |

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



Attention

Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.

• HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.

• Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

• HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other

property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

• In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

• No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production.
HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.